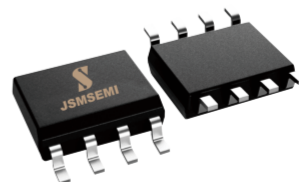


## DESCRIPTION

The RSS090P03 is the P-Channel logic enhancement mode power field effect transistor is produced using high cell density advanced trench technology..

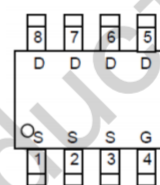
This high density process is especially tailored to minimize on-state resistance.

This device is suitable for use as a load switch or in PWM and gate charge for most of the synchronous buck converter applications

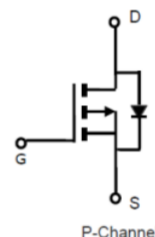


## FEATURE

- ◆ -30V/-13A,  $R_{DS(ON)} = 9\text{ m}\Omega$  (typ.)@ $V_{GS} = -10\text{V}$
- ◆ -30V/-7.0A,  $R_{DS(ON)} < 14.5\text{ m}\Omega$  (typ.)@ $V_{GS} = -4.5\text{V}$
- ◆ Super high design for extremely low  $R_{DS(ON)}$
- ◆ Exceptional on-resistance and Maximum DC current capability
- ◆ Full RoHS compliance
- ◆ SOP8 package design



TOP VIEW  
SOP-8



## APPLICATIONS

- ◆ High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/GA
- ◆ Newworking DC-DC Power System
- ◆ Load Switch
- ◆ Power Management in Note Book

## ABSOLUTE MAXIMUM RATINGS ( $T_A = 25\text{ }^\circ\text{C}$ Unless otherwise noted )

$V_{DSS}$	Drain-Source Voltage		-30	V
$V_{GSS}$	Gate-Source Voltage		$\pm 20$	V
$I_D$	Continuous Drain Current ( $T_A = 25\text{ }^\circ\text{C}$ )	$V_{GS} = 10\text{V}$	-13	A
	Continuous Drain Current ( $T_A = 70\text{ }^\circ\text{C}$ )		-9.5	A
$I_{DM}$	Pulsed Drain Current		-40	A
$I_S$	Continuous Source Current (Diode Conduction)		-2.0	A
$P_D$	Power Dissipation	$T_A = 25\text{ }^\circ\text{C}$	2.0	W
		$T_A = 70\text{ }^\circ\text{C}$	1.5	
$T_J$	Operation Junction Temperature		150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range		-55~+150	$^\circ\text{C}$
$R_{\theta JA}$	Thermal Resistance Junction to Ambient		85	$^\circ\text{C/W}$

**Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress rating only and functional device operation is not implied**

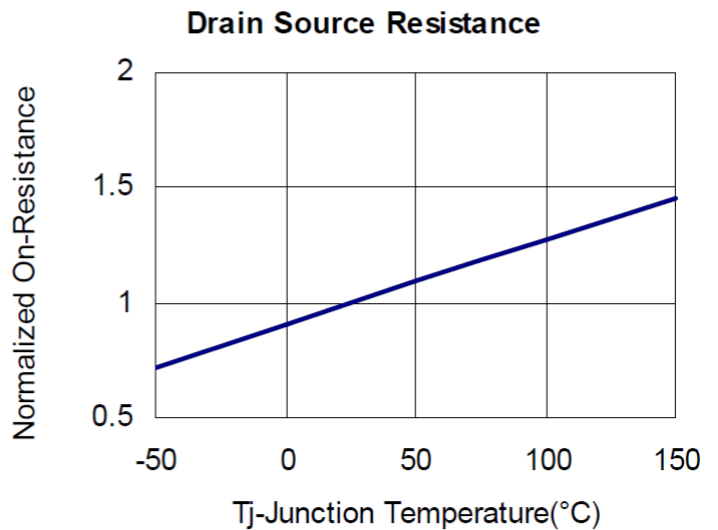
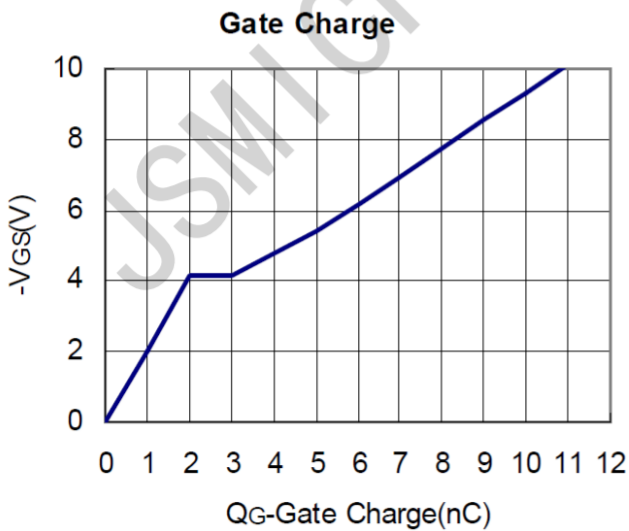
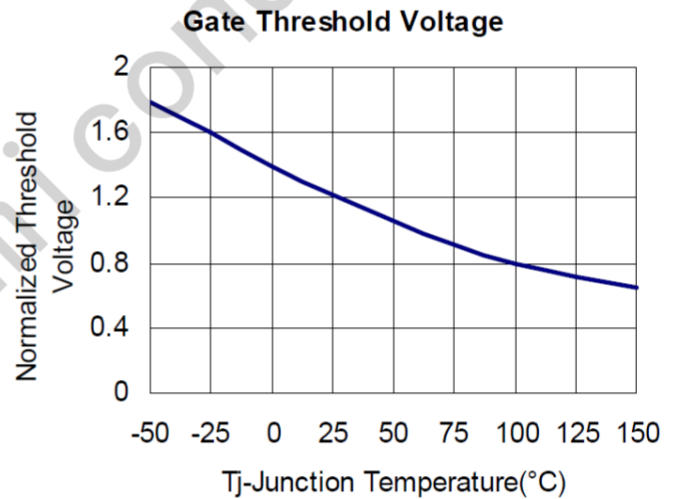
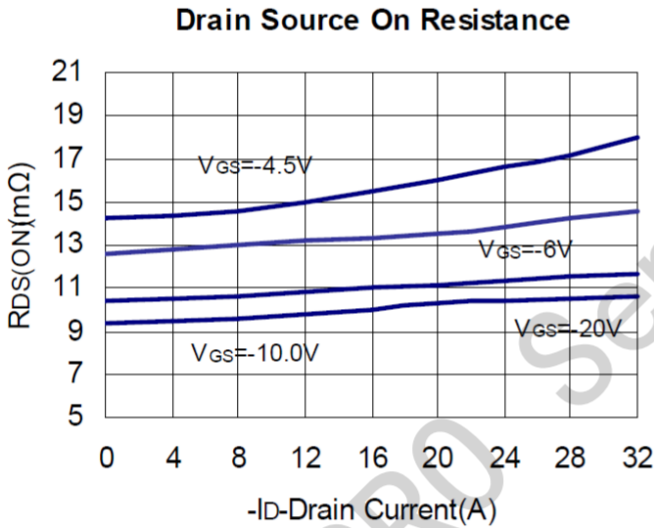
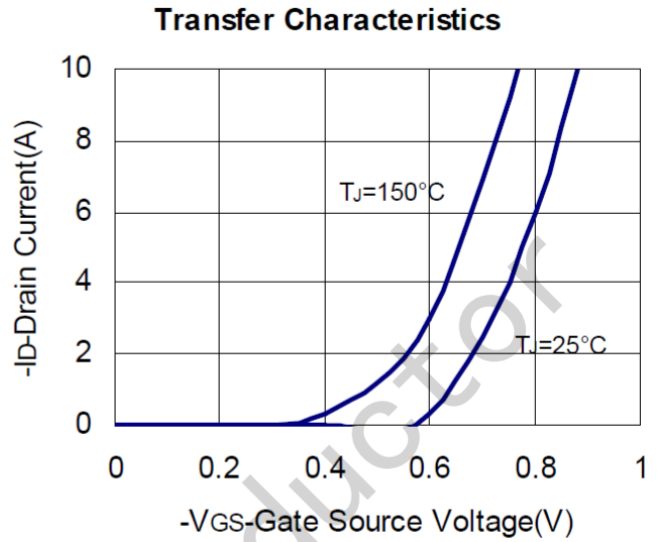
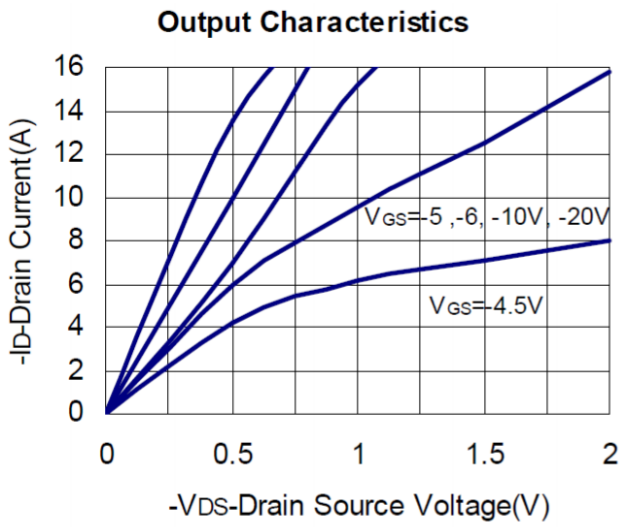
**ELECTRICAL CHARACTERISTICS** ( $T_A=25\text{ }^\circ\text{C}$  Unless otherwise noted)

Static Parameters						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-30			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.0	-1.4	-2.0	V
$I_{GSS}$	Gate Leakage Current	$V_{DS}=0V, V_{GS}=\pm 25V$			$\pm 100$	nA
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=-30V, V_{GS}=0$			-1	uA
		$V_{DS}=-30V, V_{GS}=0$ $T_J=55\text{ }^\circ\text{C}$			-5	
$R_{DS(ON)}$	Drain-Source On-Resistance	$V_{GS}=-10V, I_D=-10A$		9	13	m $\Omega$
		$V_{GS}=-4.5V, I_D=-7.0A$		14.5	17	
Source-Drain Diode						
$V_{SD}$	Diode Forward Voltage	$I_S=-2.3A, V_{GS}=0V$		-0.75	-1.0	V
Dynamic Parameters						
$Q_g$	Total Gate Charge	$V_{DS}=-15V$ $V_{GS}=-4.5V$ $I_D=-10A$		30	42	nC
$Q_{gs}$	Gate-Source Charge			10	14	
$Q_{gd}$	Gate-Drain Charge			10.4	14.6	
$C_{iss}$	Input Capacitance	$V_{DS}=-15V$ $V_{GS}=0V$ $f=1MHz$		2050	2730	pF
$C_{oss}$	Output Capacitance			506	710	
$C_{rss}$	Reverse Transfer Capacitance			420	590	
$T_{d(on)}$	Turn-On Time	$V_{DS}=-15V$ $I_D=-10A$		9.3	19	nS
$T_r$				10.2	18	
$T_{d(off)}$	Turn-Off Time	$V_{GEN}=-10V$ $R_G=3.3\Omega$		117	232	
$T_f$				24	46	

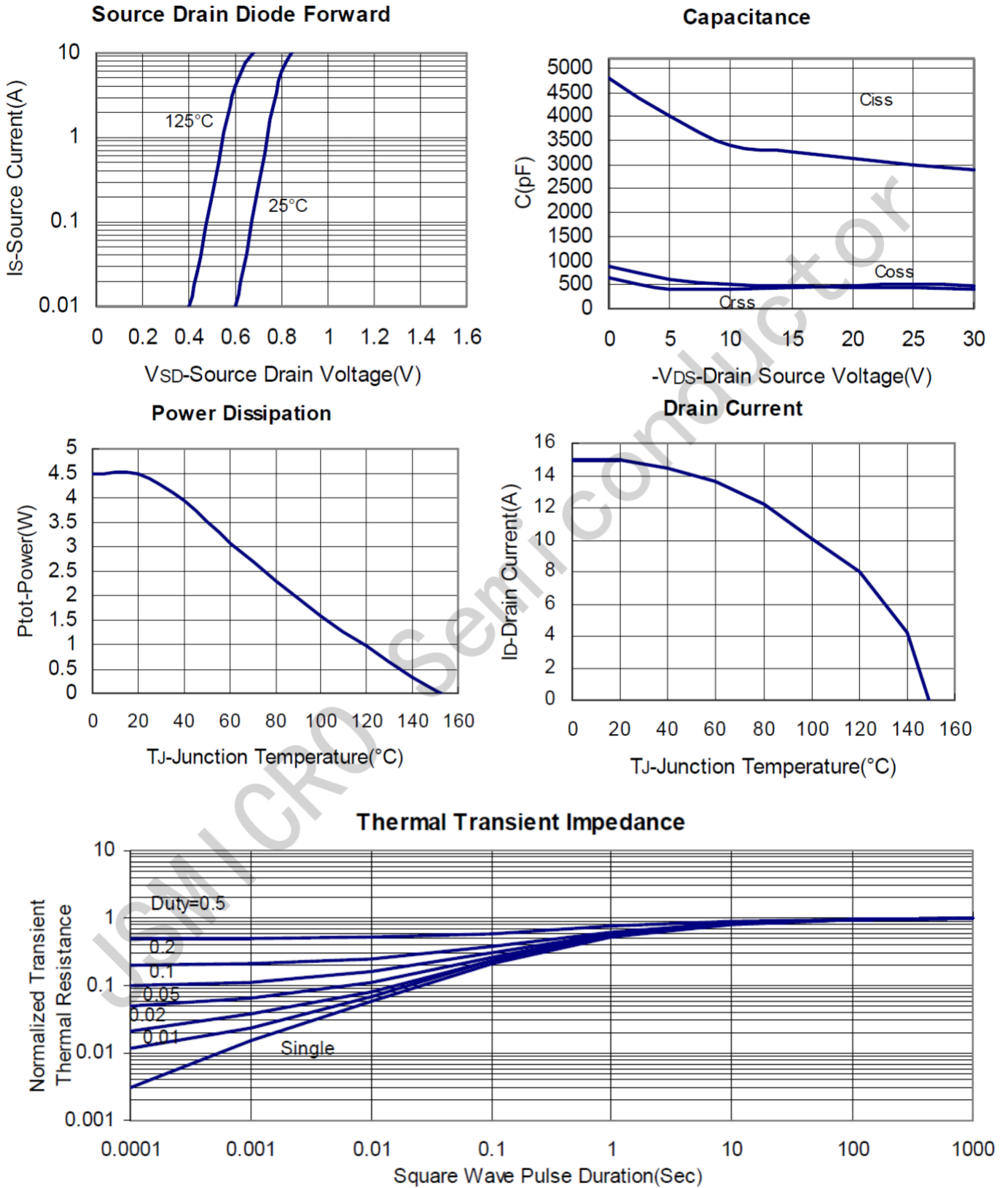
Note: 1. Pulse test: pulse width  $\leq 300\mu S$ , duty cycle  $\leq 2\%$

2. Static parameters are based on package level with recommended wire bonding

■ **TYPICAL CHARACTERISTICS** (25 °C Unless Note)

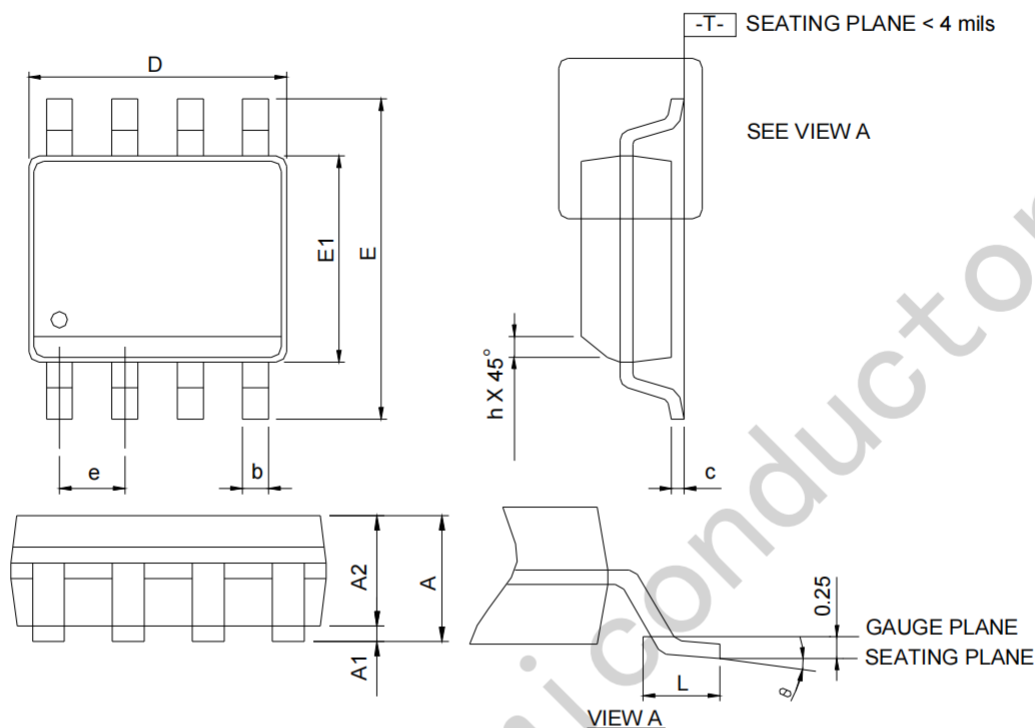


■ **TYPICAL CHARACTERISTICS** (continuous)



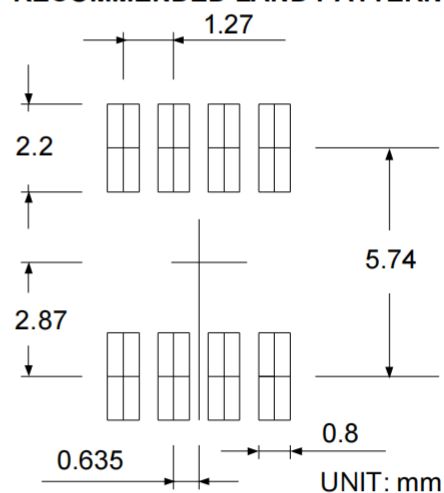
## Package Information

### SOP-8



SYMBOLS	SOP-8			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	-	1.75	-	0.069
A1	0.10	0.25	0.004	0.010
A2	1.25	-	0.049	-
b	0.31	0.51	0.012	0.020
c	0.17	0.25	0.007	0.010
D	4.80	5.00	0.189	0.197
E	5.80	6.20	0.228	0.244
E1	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
h	0.25	0.50	0.010	0.020
L	0.40	1.27	0.016	0.050
θ	0°	8°	0°	8°

### RECOMMENDED LAND PATTERN



Note: 1. Follow JEDEC MS-012 AA.

2. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 6 mil per side.

3. Dimension "E" does not include inter-lead flash or protrusions. Inter-lead flash and protrusions shall not exceed 10 mil per side.

单击下面可查看定价，库存，交付和生命周期等信息

[>>JSMSEMI\(杰盛微\)](#)